Build Up HDI (Standard)

HDI10_1+8+1_1,50_17.5_engl

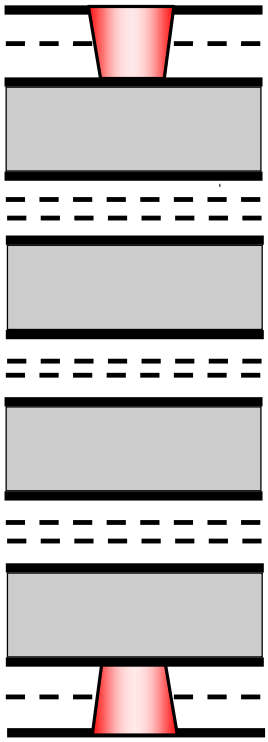
10 - Layers

Core: 0,20 mm Cu 17.5/17.5 µm

WE-Articel No.: | **1 + 8 + 1**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	66	
	2			17.5 µm		16	
			0,200 mm			200	
	3			17.5 µm		16	
					2 x 1080	134	
	4			17.5 µm		16	
			0,200 mm			200	
	5			17.5 µm		16	
					2 x 1080	134	
	6			17.5 µm		16	
			0,200 mm			200	
	7			17.5 µm		16	
					2 x 1080	134	
	8			17.5 µm		16	
			0,200 mm			200	
	9			17.5 µm		16	
					1 x 1080	66	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1486

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,50**	+/-	0,11	mm		Date:	Engineer:
thickness with electro plated Cu:	1,59	+/-	0,14	mm			
total thickness with soldermask	1,65	+/-	0,16	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision		
27.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R. Schönholz	00	page:	4+